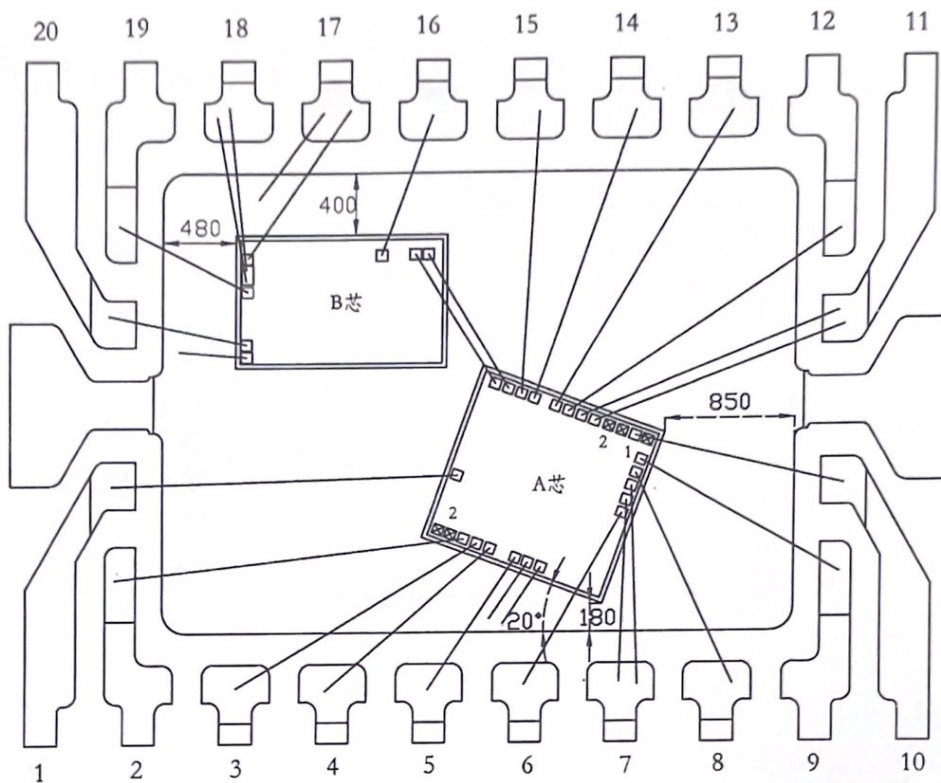
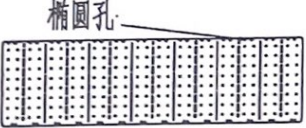
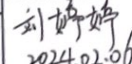
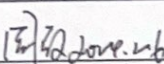
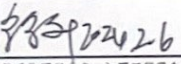
 池州华宇电子科技股份有限公司 CHIZHOU NISEMI ELECTRONICS TECHNOLOGY CO., LTD 焊线图纸 Bonding Diagram				客户代码 Customer No.	008	图号 Drawing No.	HY-PX-008-733 A	
产品名称 Product Type				HS24G003N		封装类型 PKG Type		TSSOP20
焊线种类 Wire Type	焊线直径(μm) Wire Diameter	焊线根数 NO. of wire	焊线总长(μm) Total wire length	最长焊线(μm) Longest wire length	最短焊线(μm) Shortest wire length	焊线材料(绿色环保) Compound Type (Green)		LF 载体尺寸 LF Pad Size
合金丝 Ag	20	29	45794	2329	442	首选(Preferred): EDML-G630AY 备选(Optional): CEJ-1702HP		TSSOP20PL-88 (118X16mil) 3000XAG88mm ²
客户图号 Customer drawing NO.								



框架特透方向(载片): I/P Direction (D/A): 	实物图: Chip photo:	特殊说明 Special Instructions: DB注意: 1. 以施工要求按顺序装片, 如: 先装A芯片, 装B芯片时必须 在有A芯片的框架, 反之先装B芯片, 装A芯片时B芯片已装片; 2. 控制温度, 为WB预留焊线位置; WB注意: 1. 数字为PAD不打线个数; 2. 植焊点在B芯;
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说明 Description	贴片胶类型 Epoxy type	芯片名称 Die name	芯片尺寸 Die Size	最小焊盘尺寸 Min BPP(μm)	最小焊盘间距 Min BPP(μm)	焊盘厚度(μm) Pad Thickness	焊盘下是否有电路 Circuit under Pad	划片线宽度 Scribe line (μm)	晶圆尺寸 Wafer Size	是否足 Learn No. (100mm x 100mm)	晶圆厚度 Wafer Thickness
A芯: DIE A	导电胶 (conducity) SS02	HSS129	1239*1138(μm) ² 48.78*44.80(mil) ²	70*65	60	0.8	是/Yes	60	8	否/NO	200
B芯: DIE B	导电胶 (conducity) SS02	NTU003A	1342*804(μm) ² 52.83*31.65(mil) ²	60*60	60	2.0	是/Yes	60	8	否/NO	200
C芯: DIE C											

制图日期 Create Date	2024/2/5	生效日期 Effective Date		客户确认签字/盖章: Customer Signature	 2024.02.06
编制 Prepared by		审核 Checked by		批准 Approved by	

温馨提示: 图纸由产品下线生产的一体图, 请您认真确认, 我司能帮您回签的图纸生产, 如图纸错误会产生不可估量损失, 谢谢!
 Warm tips: the drawing is the only basis for the production of the product. Please confirm it carefully. Our company will produce the drawings according to the drawings you have signed back, such as
 drawing mistakes, which will produce inevitable loss. Thank you